



Training Program

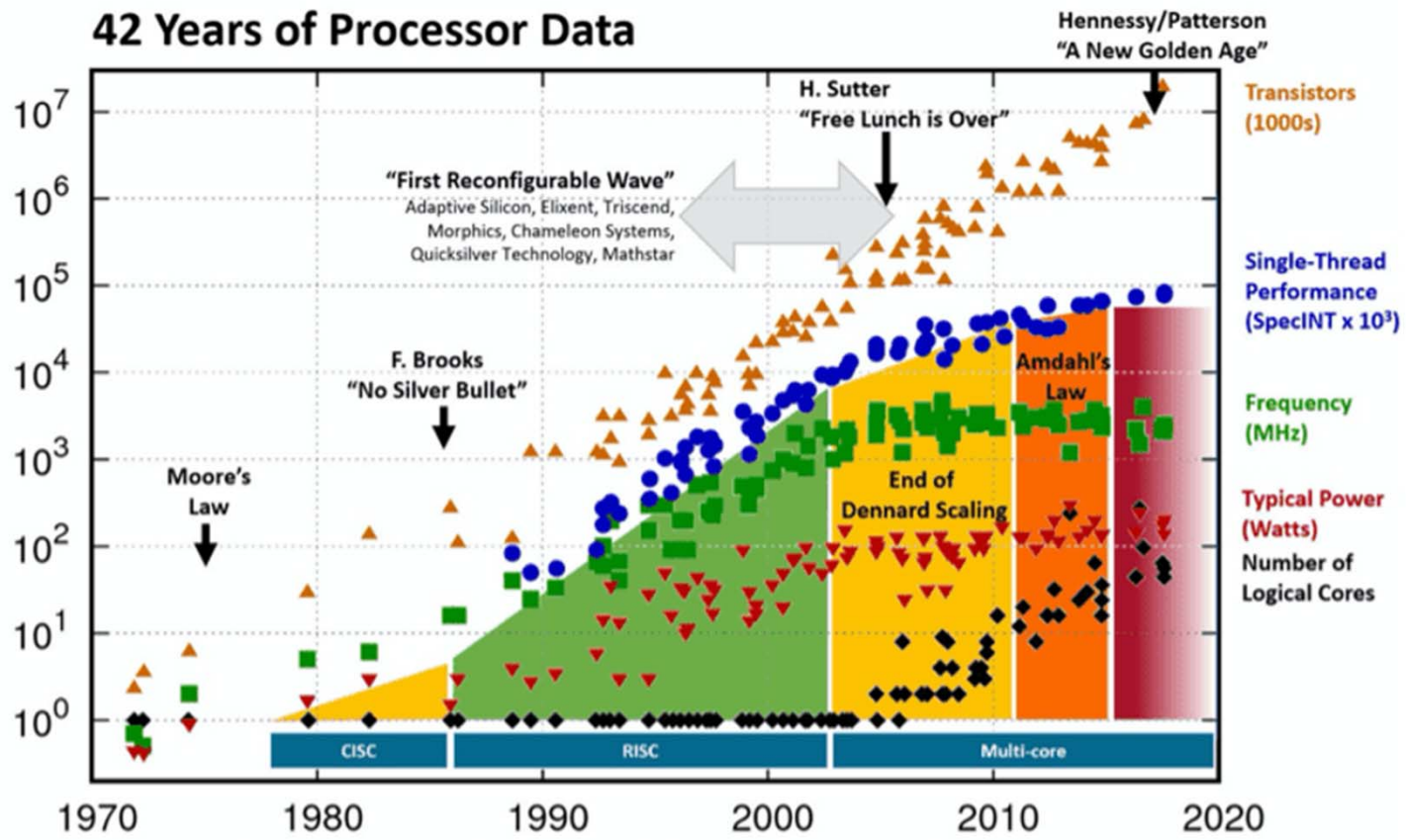
Mark Horowitz
horowitz@ee.Stanford.edu

Why A HEPIC Design Apprenticeship Program?

Two questions:

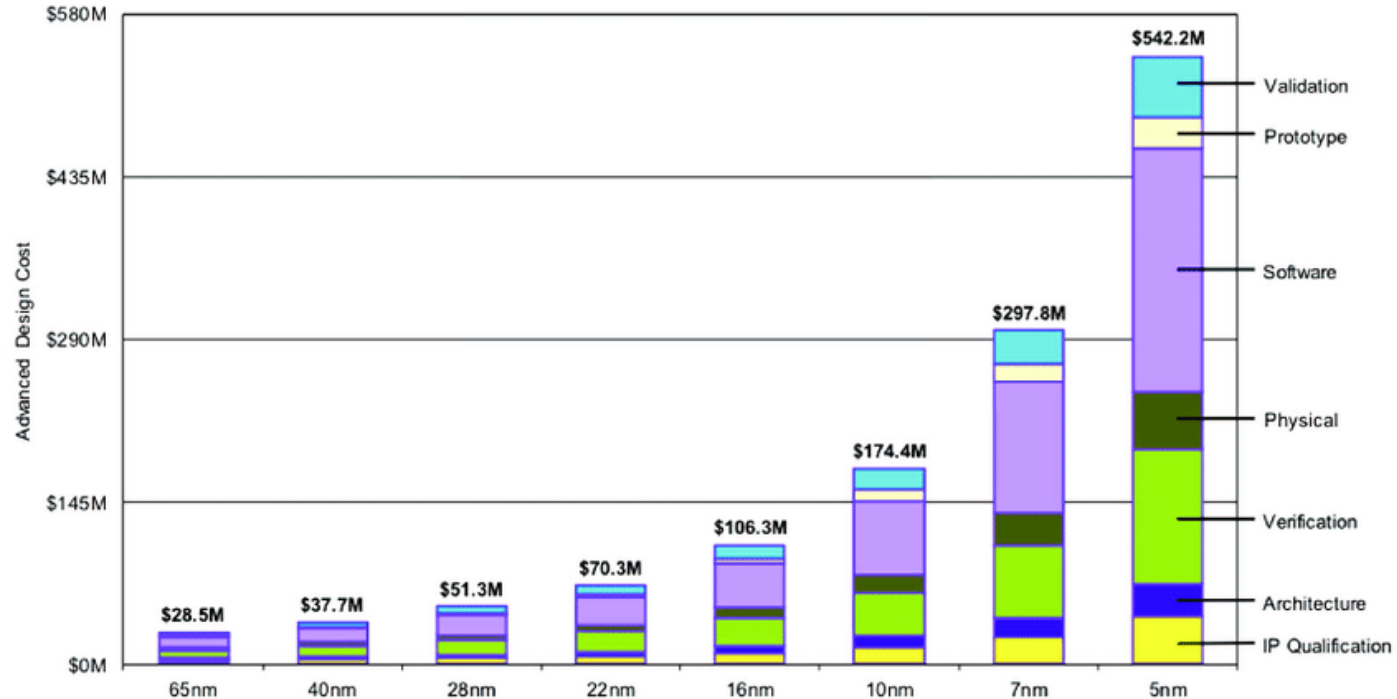
- Why does HEP need ICs
 - › I think that is easy for those at this conference
- Why do we need a Design Apprenticeship program
 - › In 2021 interest in chip design was in decline

We Are Burdened By Our Own Success



Hennessy and Patterson, Turing Lecture 2018, overlaid over "42 Years of Processors Data"
<https://www.karlrupp.net/2018/02/42-years-of-microprocessor-trend-data/>; "First Wave" added by Les Wilson, Frank Schirrmeyer
 Original data up to the year 2010 collected and plotted by M. Horowitz, F. Labonte, O. Shacham, K. Olukotun, L. Hammond, and C. Batten
 New plot and data collected for 2010-2017 by K. Rupp

Complex Systems Are Expensive To Design



Chip Design and Manufacturing Cost under Different Process Nodes: Data Source from IBS

Leads To Industry Consolidation

Consolidation in the semiconductor industry

160
COMPANIES



10 Years Ago

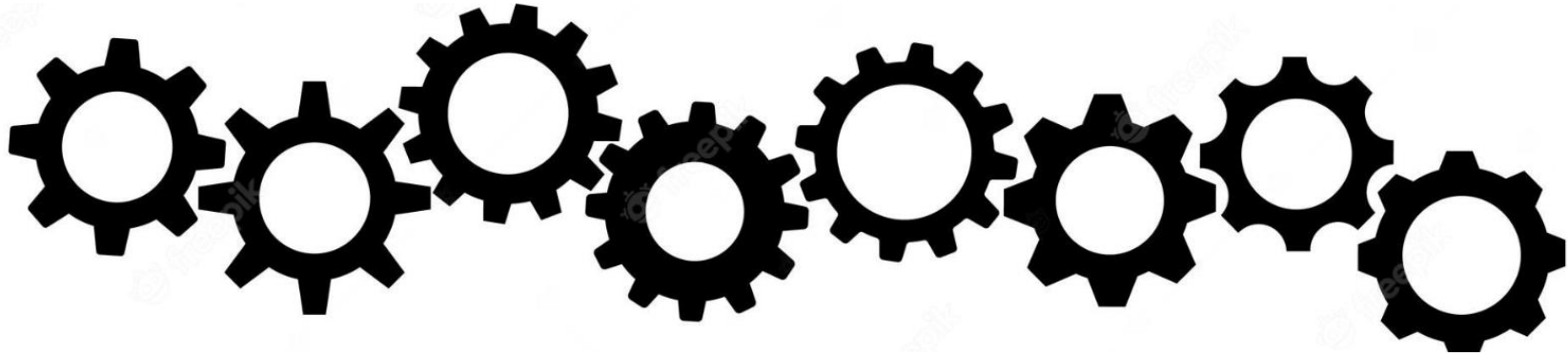
97
COMPANIES



Today

Source: Accenture Analysis of S&P Capital IQ data as of November 2020.

And Lower Student Interest In Hardware



And those students interested in IC are snapped up by industry

Solve Two Problems w/ One Program

Using interesting HEP-IC design challenges at National Labs

- To generate interest in IC design
- To introduce students to opportunities in HEP-IC design

Three-Pronged Program

- University classes
- SLAC Summer school
- National Lab projects

Digital

CS107E

Computer Systems
from the Ground Up

Chris Gregg

EE108

Digital System
Design

Subhasish Mitra

EE180

Digital Systems
Architecture

Christos Kozyrakis

EE282

Computer Systems
Architecture

Caroline Trippel

EE271

Introduction to
VLSI Systems

Priyanka Raina

CS357S

Formal Methods

Caroline Trippel

EE272

Design Projects in
VLSI Systems I

Priyanka Raina

EE156/256

Board Level Design

Steve Clark

EE372

Tapeout Class
Design Projects in
VLSI Systems II

Priyanka Raina

EE273

Digital Systems Engineering

Mark Horowitz

ENGR 40M

An Intro to Making

Tom Lee

EE292A

EDA & ML

Raul Camposano

EE207

Neuromorphics:
Brains in Silicon

Kwabena Boahen

EE309A

Semiconductor Memory Devices
and Circuit Design

Philip Wong, Priyanka Raina

EE309B

Emerging Non-Volatile Memory
Devices and Circuit Design

Philip Wong, Priyanka Raina

Analog

EE101A

Circuits I

Eric Pop

EE101B

Circuits II

Tom Lee

EE114 / EE214A

Fundamentals of Analog
Integrated Circuit Design

Amin Arbabian

EE214B

Advanced Integrated Circuit
Design

Angelo Dragone

EE315

Analog-Digital
Interface Circuits

TBD

EE314A

RF Integrated
Circuit Design

Amin Arbabian

EE114/214A: Fundamentals of Analog Integrated Circuit Design

Learning Goals:

Specific Analog Circuit Concepts:

CMOS transistor models, biasing, amplifier stages, frequency response, differential and multi-stage amplifiers, circuit non-idealities, feedback, noise, & stability

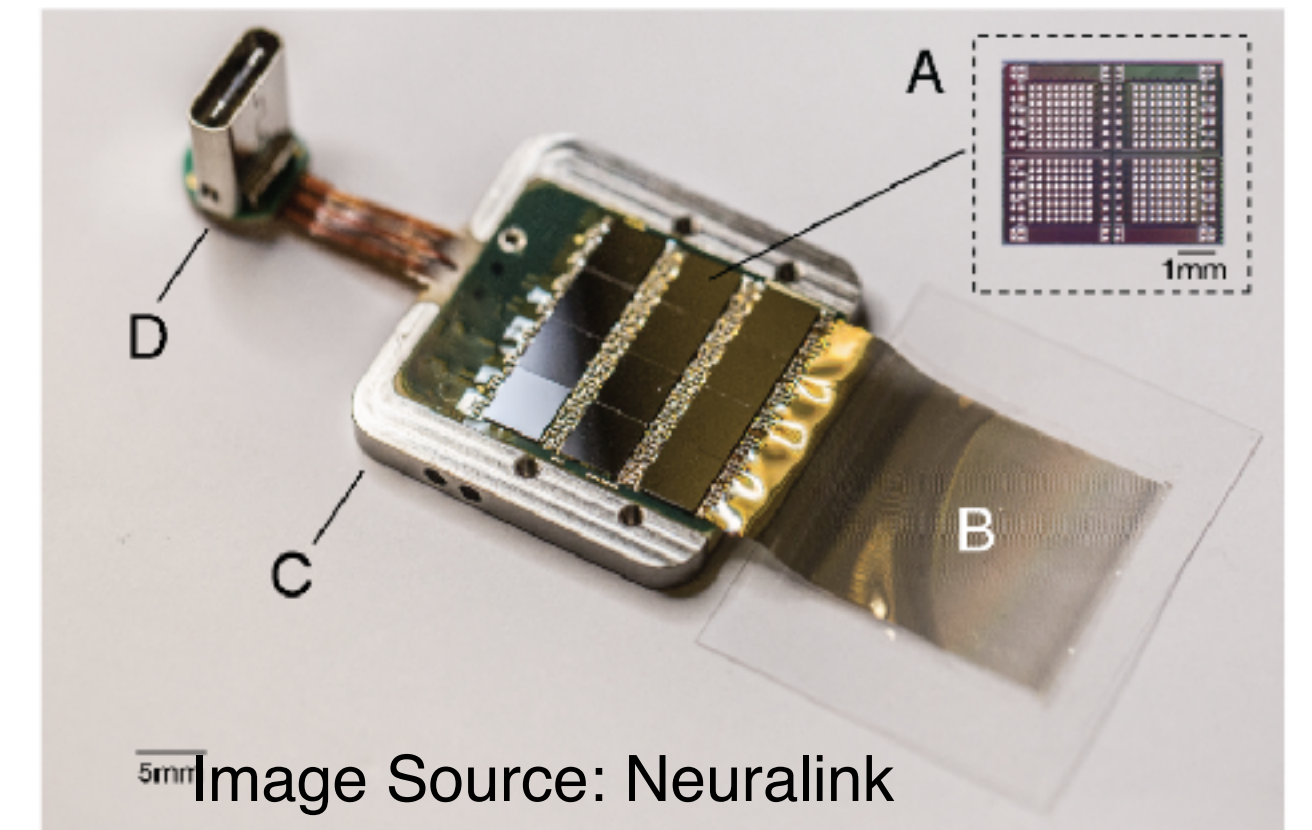
Intro to Design Methodology *:

- Abstraction
- Modeling
- Analysis
- **Design**
- Verification

* Applies more broadly than analog circuits

Example applications of analog circuits for sensor interfaces:

1) Neural interfaces



2) LiDAR systems for self driving cars

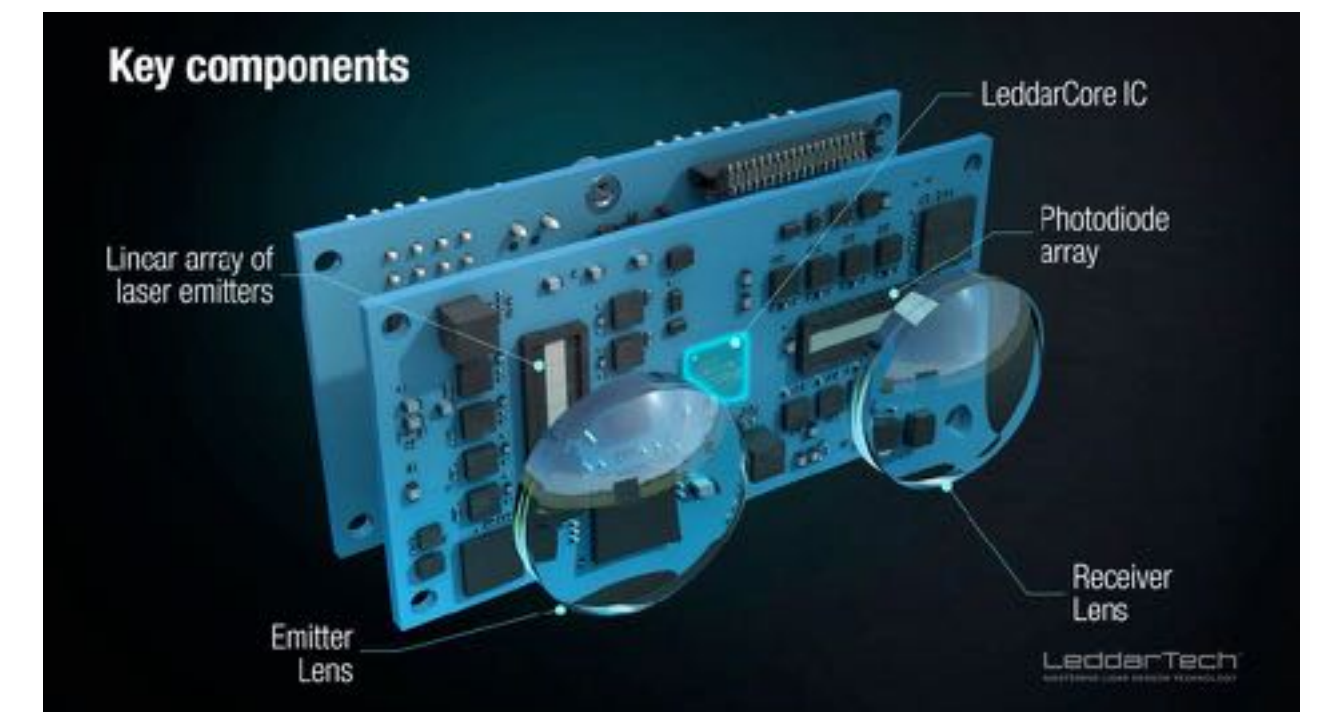
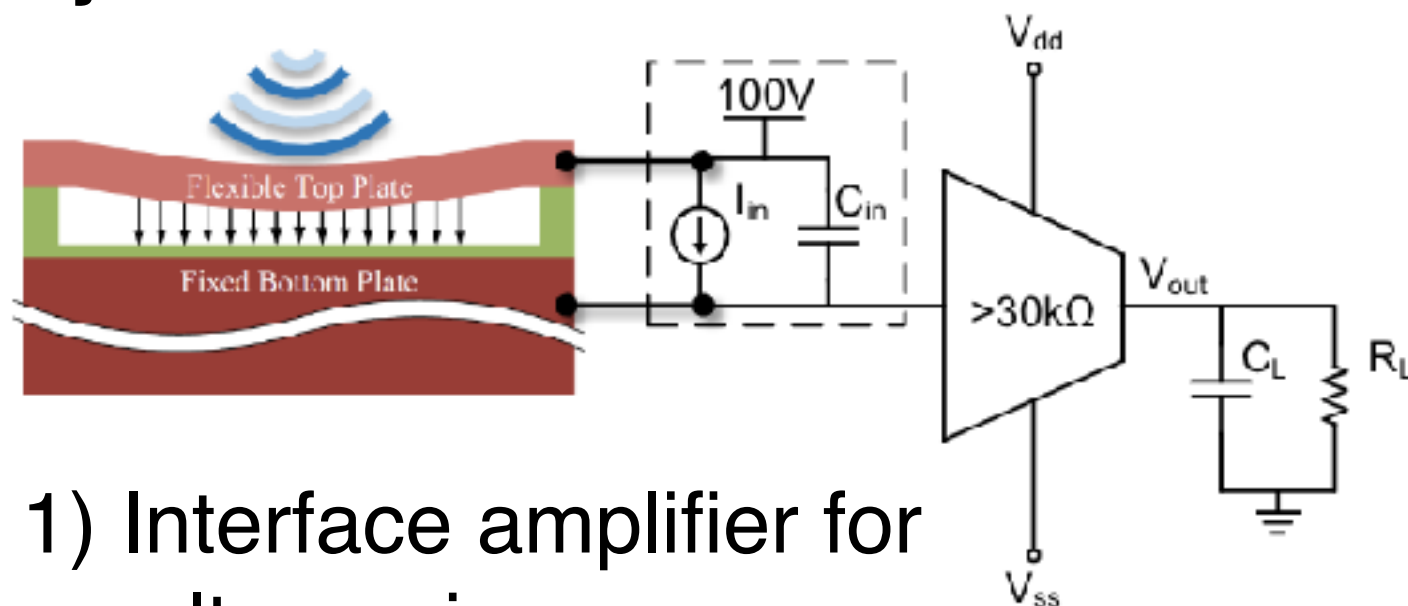
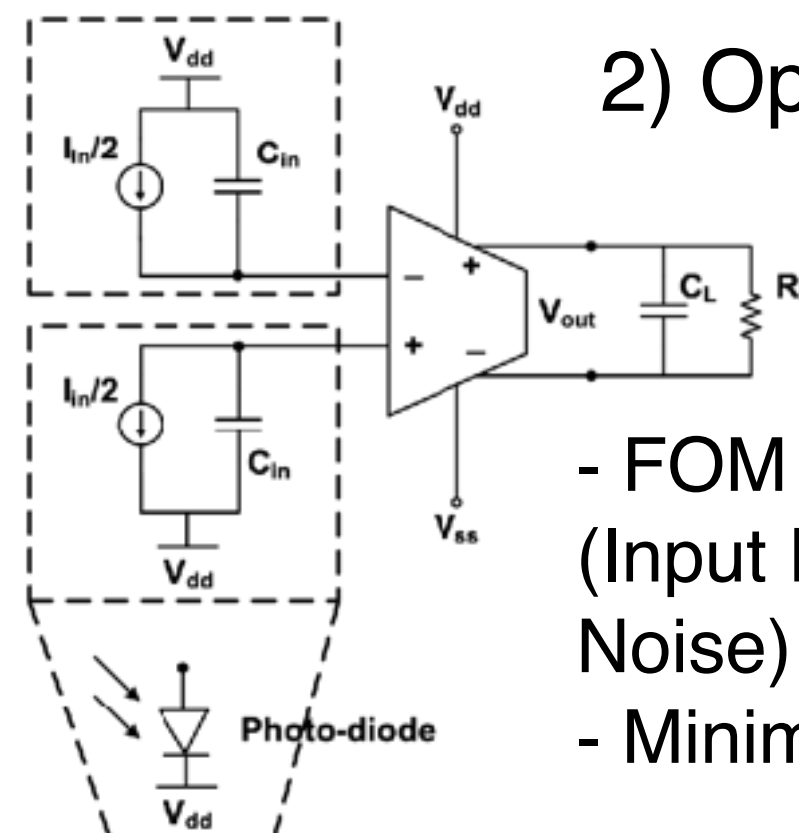


Image Source: LeddarTech Inc.

Example Design Projects:



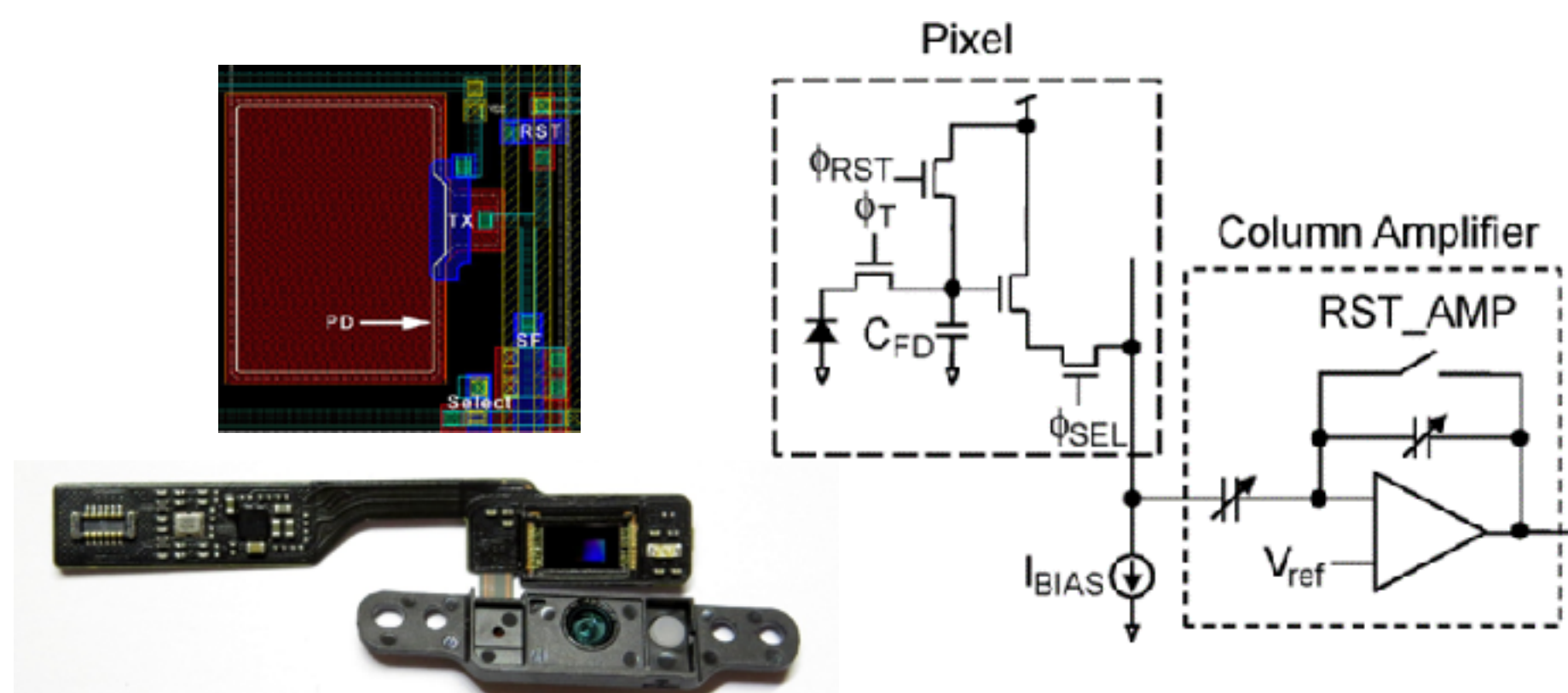
1) Interface amplifier for an ultrasonic sensor



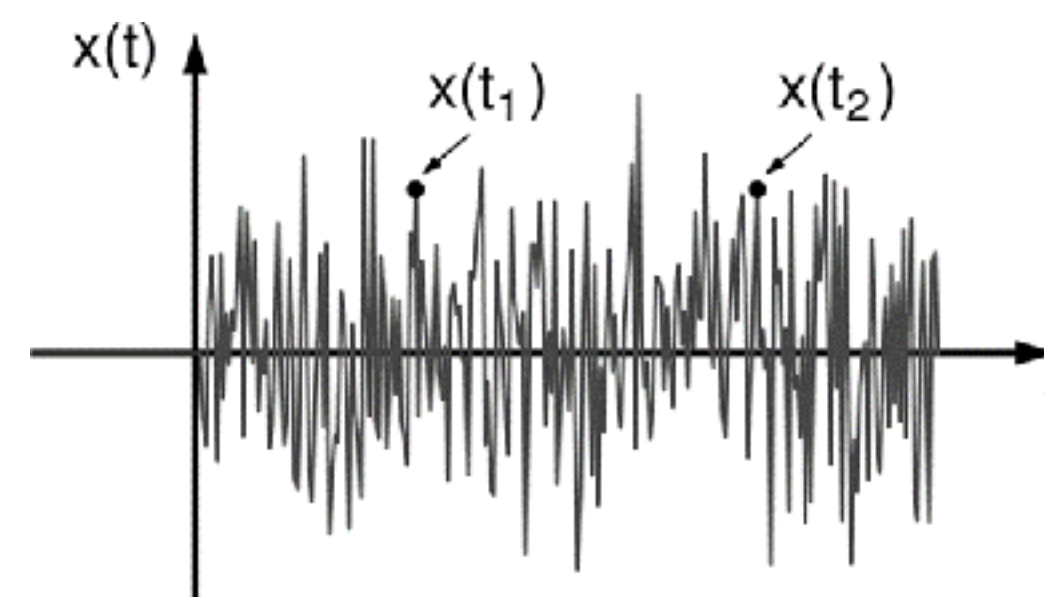
2) Optical sensor circuit

- FOM : (Gain x Bandwidth)/ (Input Referred Differential Noise)
- Minimize power consumption

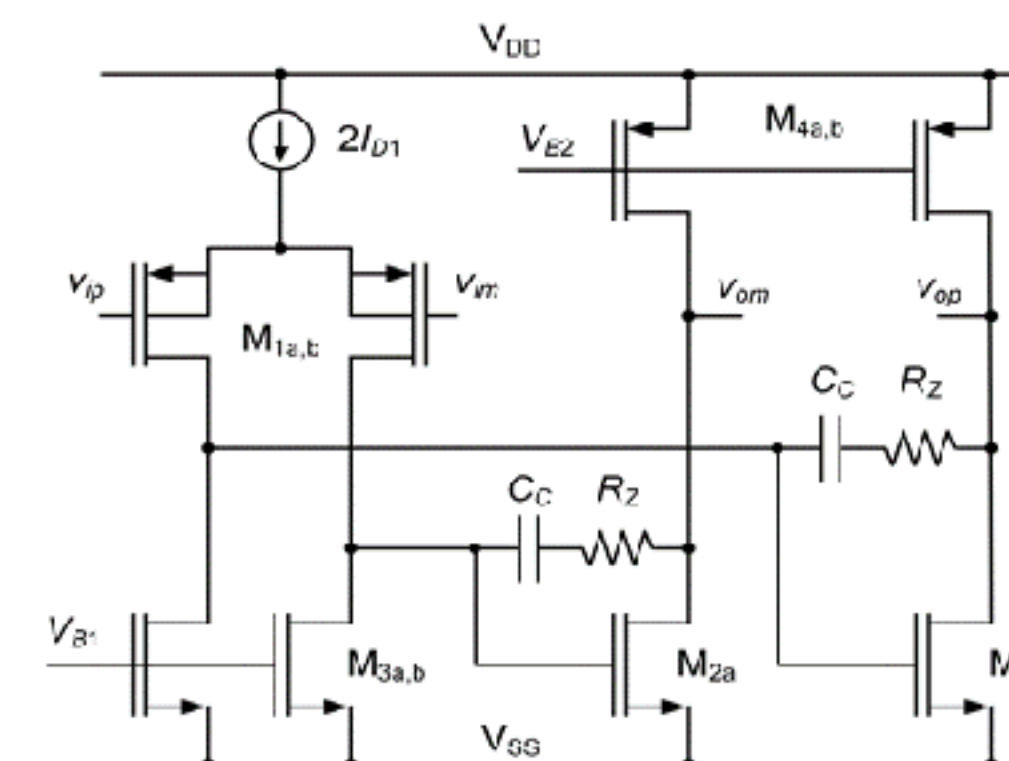
EE214B: Advanced Integrated Circuit Design



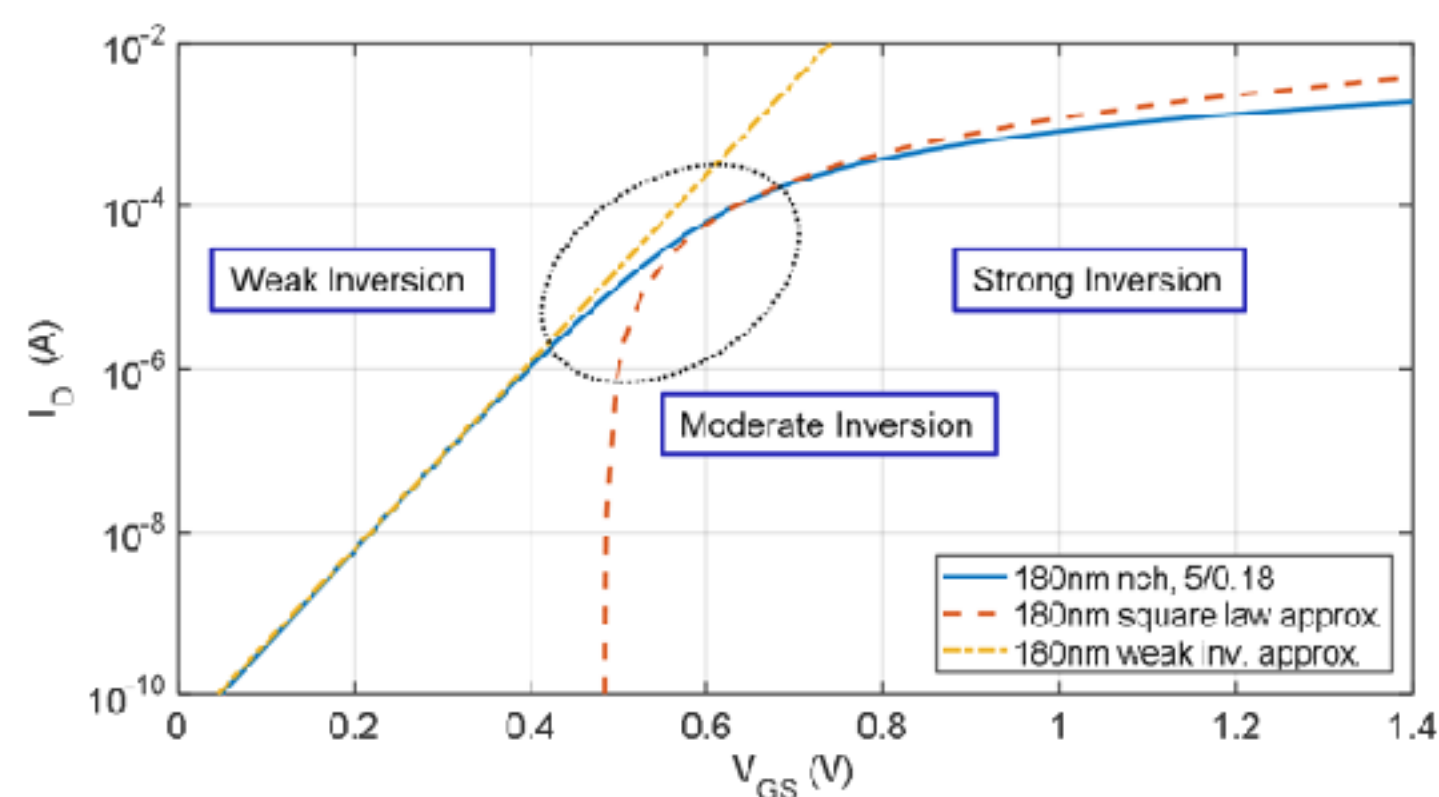
Driver Application: Image sensor



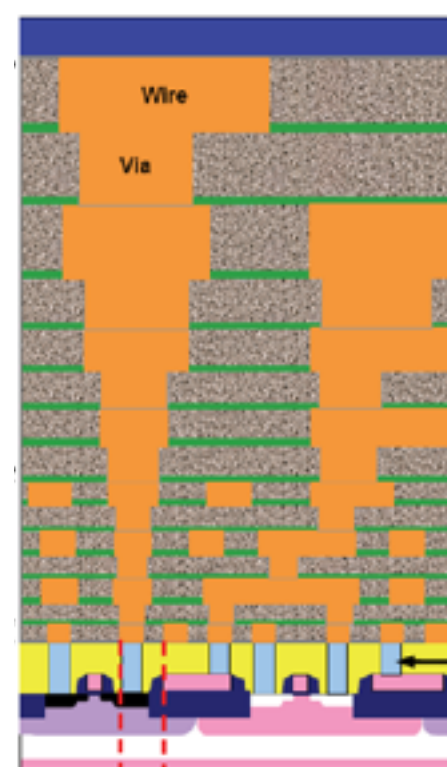
Noise analysis



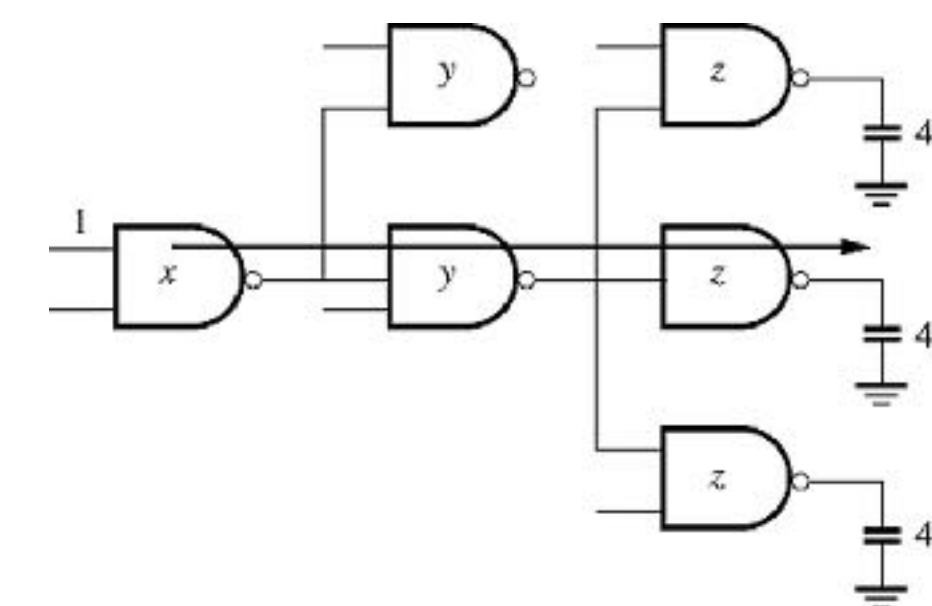
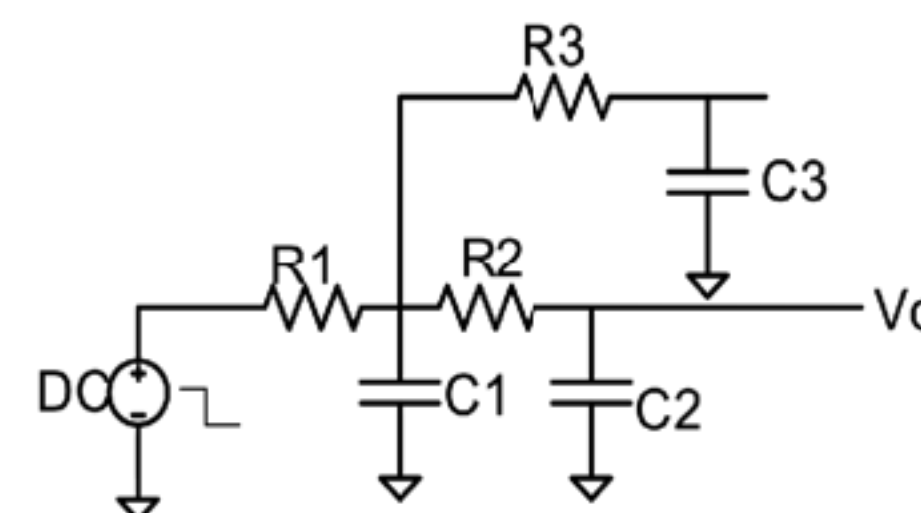
Amplifier design



Transistor modeling

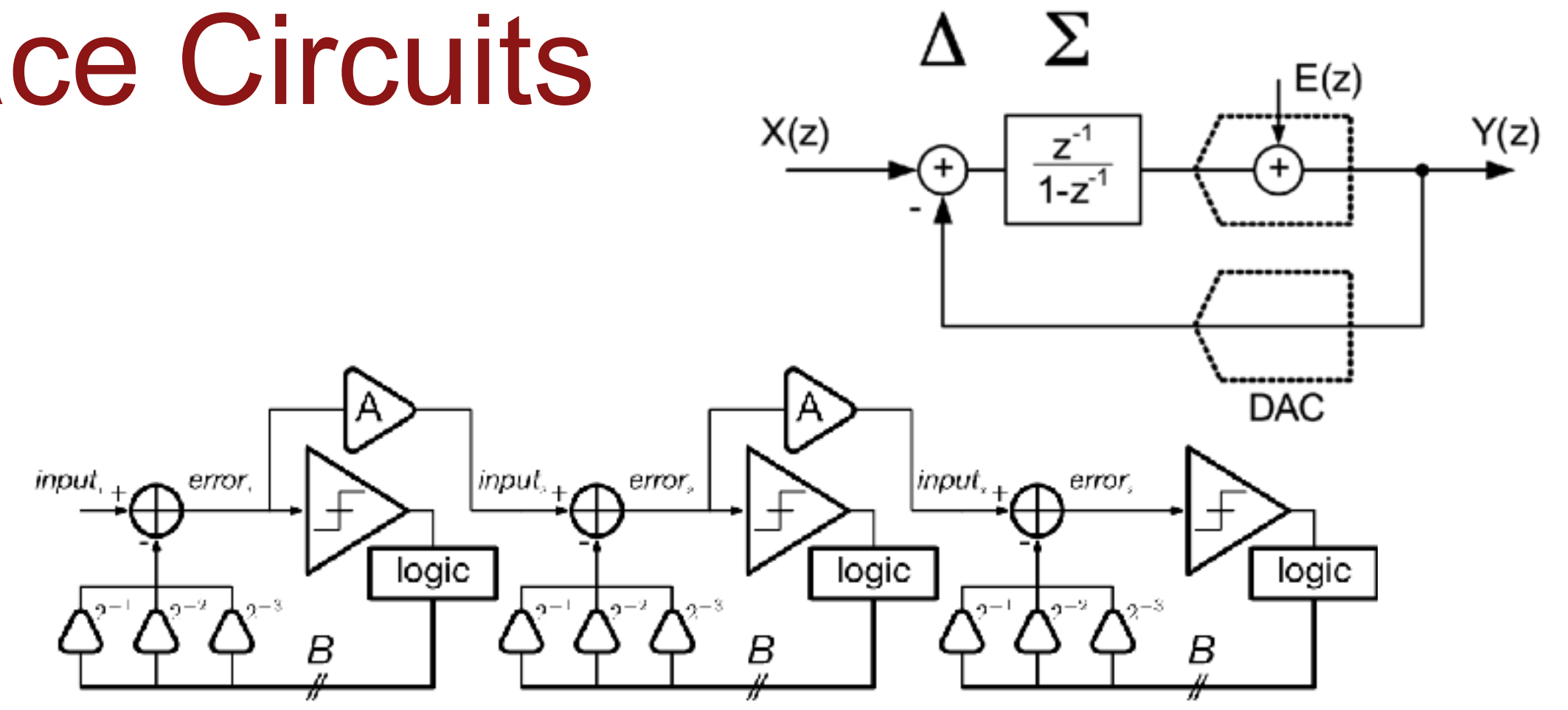
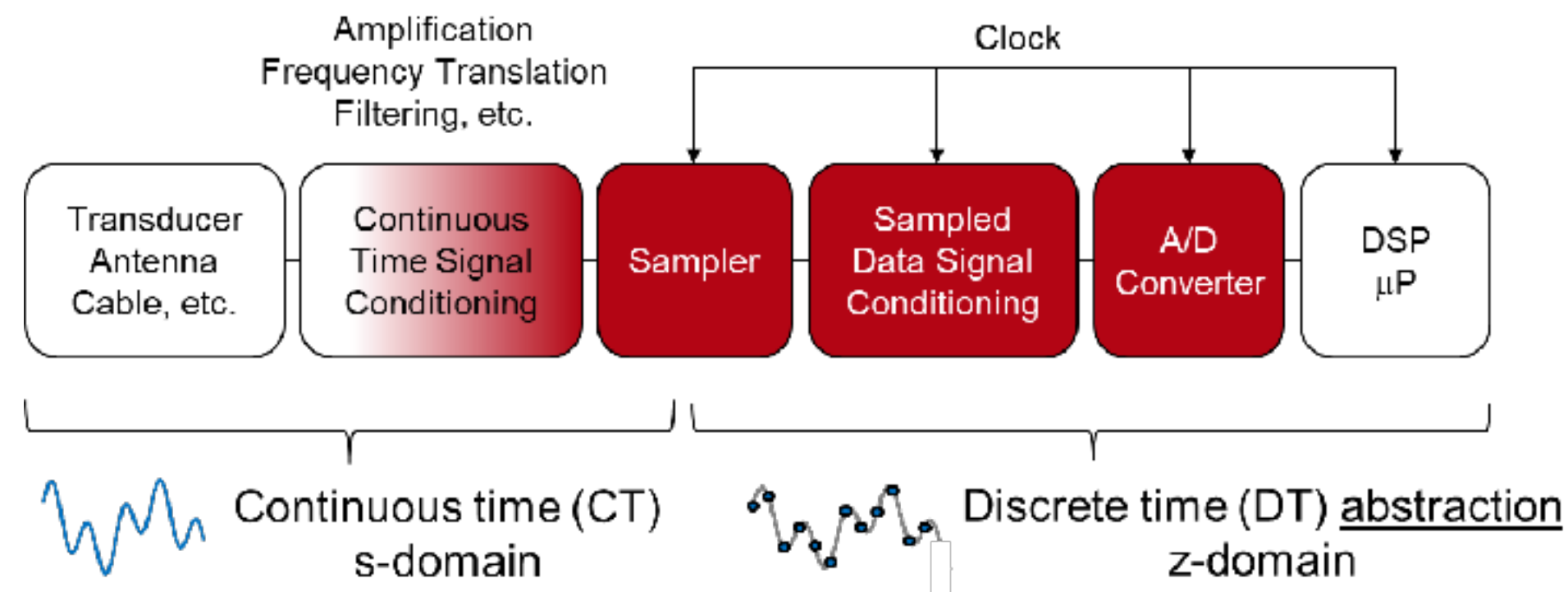


Interconnect modeling

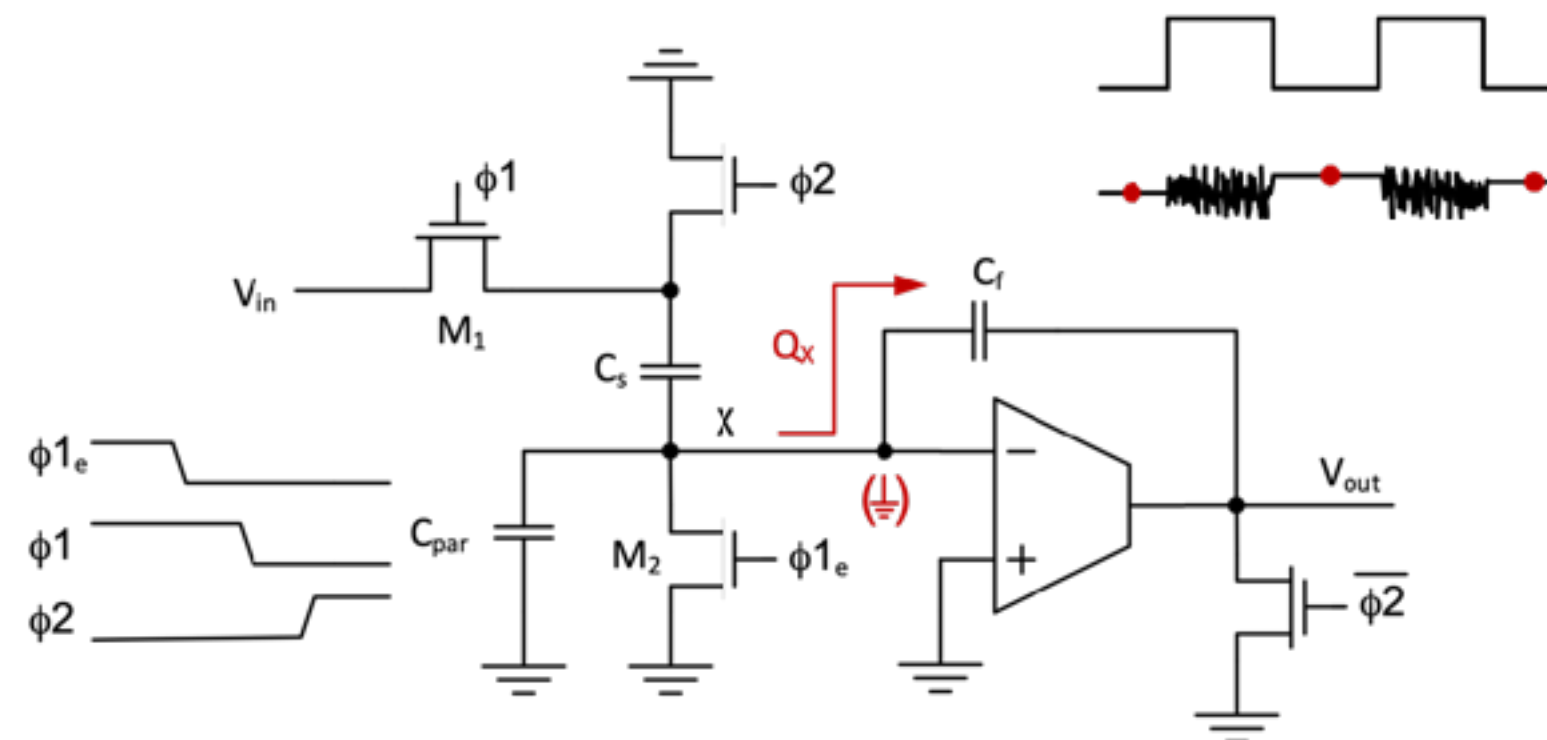


Gate sizing

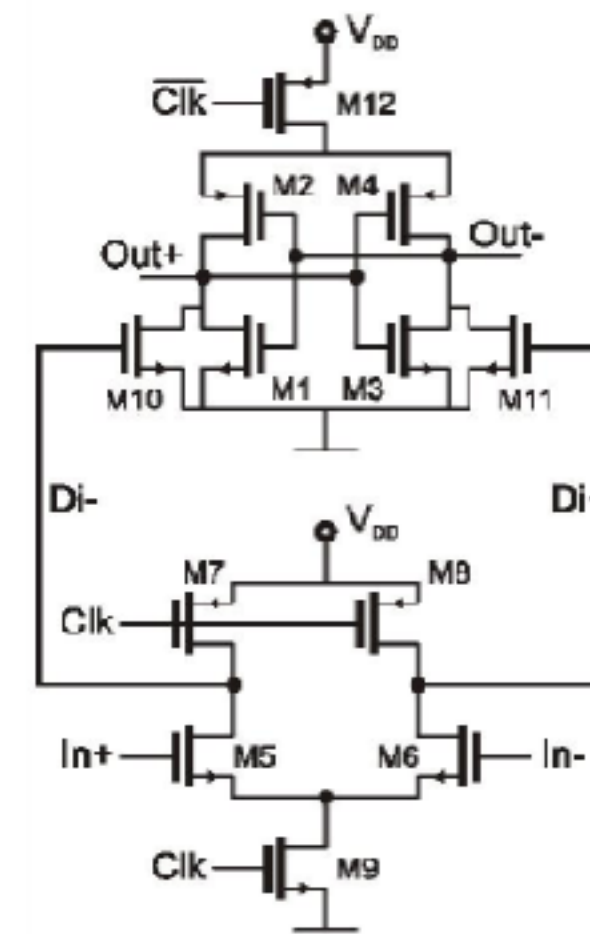
EE315: Analog-Digital Interface Circuits



Modeling of A/D and D/A interfaces

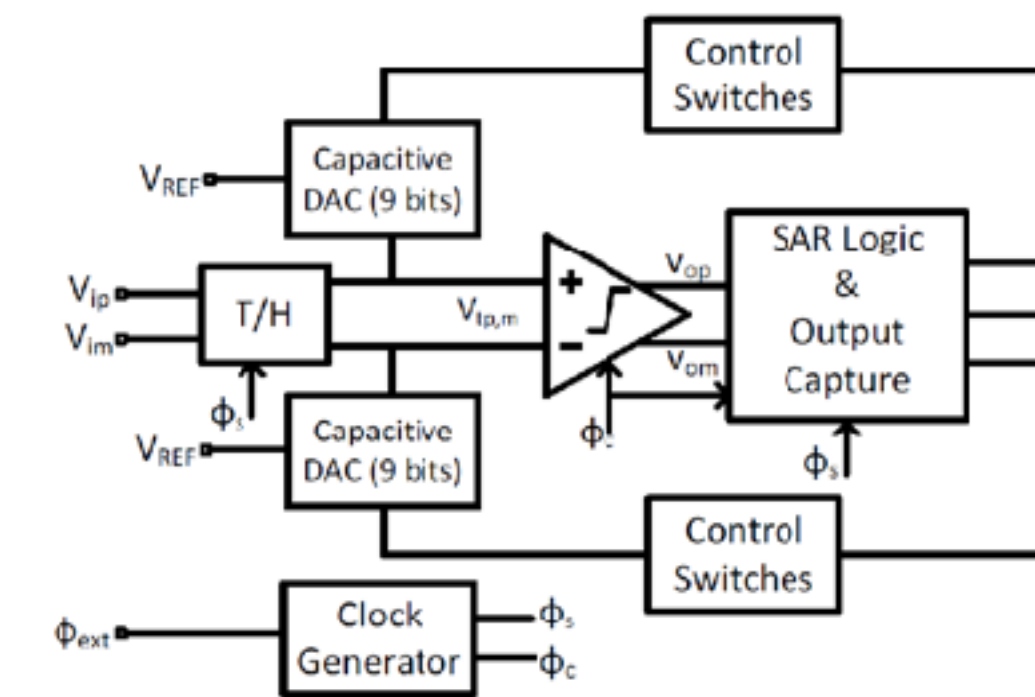


Switched capacitor circuits, filters



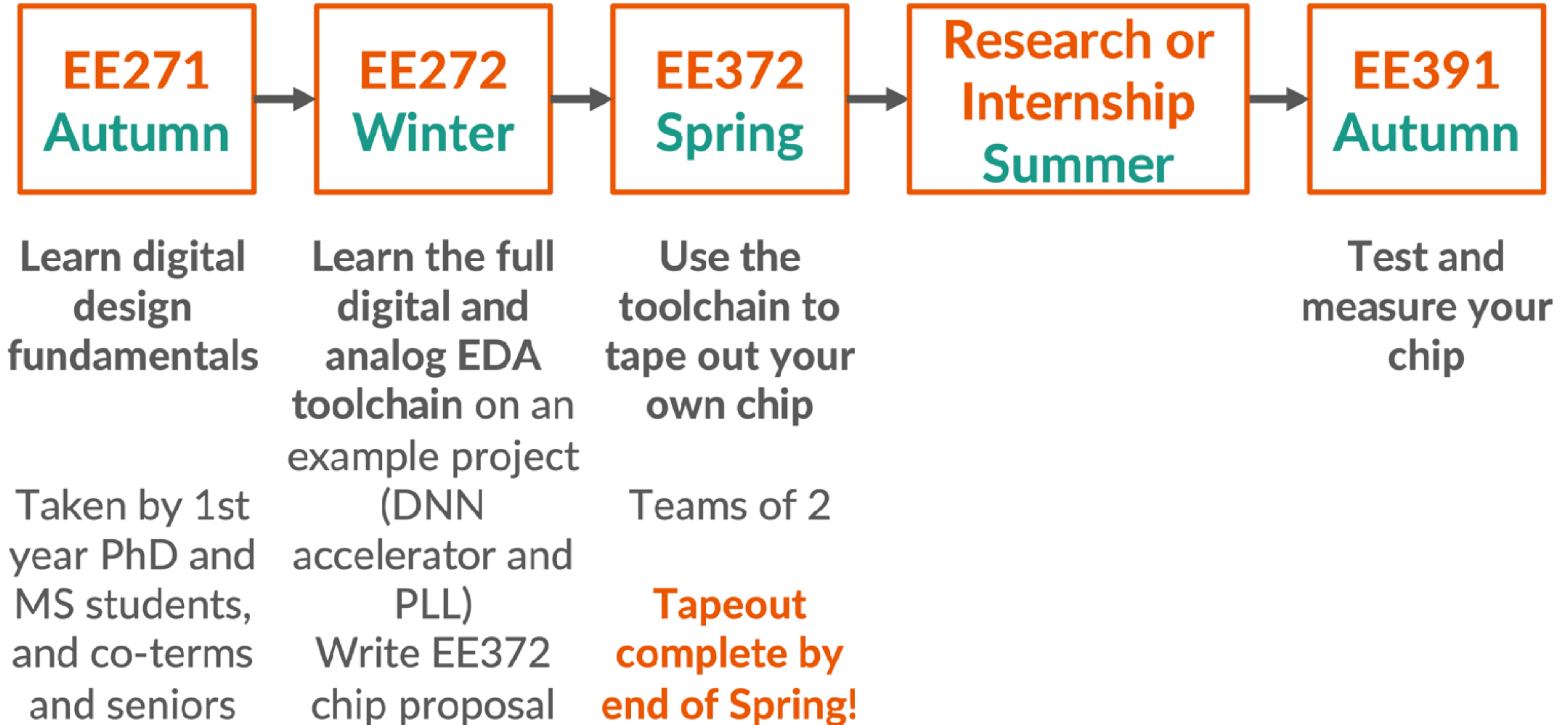
Comparators

A/D and D/A converters



Project: SAR ADC

VLSI Design Course Sequence





Summer Week

- Goals:
- **Aimed at graduate IC design students but open to others at a similar level. This summer week will cover High Energy Physics use cases and unique operating conditions, such as high radiation or deep cryogenic temperature.**
- Program:
- **A mix of lectures and practical design exercises:**
- **Students will attend lectures on HEP topics in the morning and will work together in teams in the afternoons on solving design exercises. The teams will present the results on the last day of the workshop.**
- Lectures over the past years have included:
- Analog front-end design, ADCs, fast timing circuits, digital flow, cryogenic readout circuits, introduction to particle physics, experimental collider physics, cryogenic detectors, and accelerator physics.

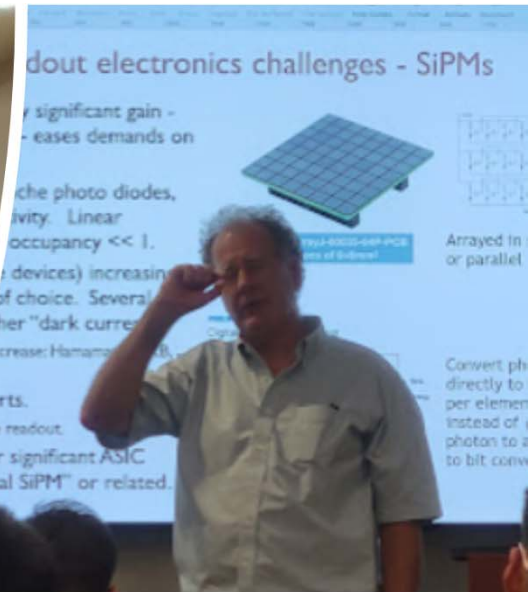


Highlights:

- ~20 participants (Ma-Postdoc)
- 4.5 days
- 4 plenary lectures on high-energy physics
- 4 plenary lectures on instrumentation
- 4 afternoons of IC design time
- 1 student presentation session

Testimonials and impressions

- 'I learned a lot in terms of physics of colliders and accelerators and how that physics is translated to hardware design and circuits. As a non-expert in IC, I learned a lot about circuits and their components.'*
- 'Thank you for this amazing experience, I had a lot of fun and enjoyed meeting the other students.'*
- 'Before participating in this program, I had very limited knowledge about High Energy Physics detectors. After experiencing the lectures, tours, and working on the design challenge, I am definitely intrigued by the prospect of designing readout ASICs for HEP detectors.'*



Sign-up Now For The Next Edition!

High Energy Physics (HEP) IC Design Traineeship Program

SLAC National Accelerator Laboratory. Menlo Park, California

June 24 - 28, 2024

<https://indico.slac.stanford.edu/event/8802/>

Final deadline for registration: June 1st. Currently 9/20 slots are filled.

Program Organization

During Fall Quarter

- Students find out about program during graduate orientation
- They apply to the program, and start taking IC design classes
- PIs review applications and select apprentice

During Winter Quarter

- Lab propose projects
- Virtual meeting where projects are introduced
- Student – lab project matching process

Program Organization, cont'd

Spring Quarter

- Students continue to take IC design classes
- Start talking with their lab about their project

Summer Quarter

- SLAC summer school
 - › Brings all the students together
- Work on their project at their lab.

Following year, they continue working on their degree

- Usually continue some connection with lab

Program Progress

First year had 3 students

- SLAC, Fermi, BNL
 - › Two students converted from MS to PhD
 - › One is doing his PhD at SLAC

Second year had 5 students

- SLAC, LBL, Fermi

Current year has 7 students

- SLAC, LBL, Fermi, BNL

How Funding Works

Funding is restricted to around \$55k

- Direct student support, no overhead
- But smaller than annual cost of student at Stanford

Stanford, UCSC, UCD

- Are on quarter system
- Students are selected fall quarter
- Support students in Winter, Spring, Summer

Conclusion

The program is running well

- Would be better to have a larger pool of students

Please reach out if you are interested in joining